

# RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS1643 (w/BR1225)	Nov-96	9644 B2	DALLAS	DA086954	N/A	28 MODULE

**STRESS/JOB NO.**

**READPOINT**

(Sample Size/No. of Fails)

Hi Temp Storage 70°C, No Bias P-18592, P-18634	<u>0 Hr</u>	<u>336 Hr</u>	<u>1K Hr</u>	<u>Elect. Test</u>	<u>Cum %</u>
	90/0	20/0	20/0	20/0	0.0%

Temp Cycle 0°C to +70°C P-18635	<u>300 ~</u>	<u>1K ~</u>	<u>Elect. Test</u>	<u>Cum %</u>
	35/0	35/4 F1	31/0	11.4%

Moisture Soak 60°C/90% RH P-18636	<u>288 Hr</u>	<u>960 Hr</u>	<u>Elect. Test</u>	<u>Cum %</u>
	35/0	35/0	35/0	0.0%

Phys. Dimen. <u>P-18591</u>	Solderability <u>P-18590</u>
6/0	24/0

**Failure Mode**

F1: 4-Slow Time

**Failure Analysis**

In process